CEPC Hadron Calorimeter

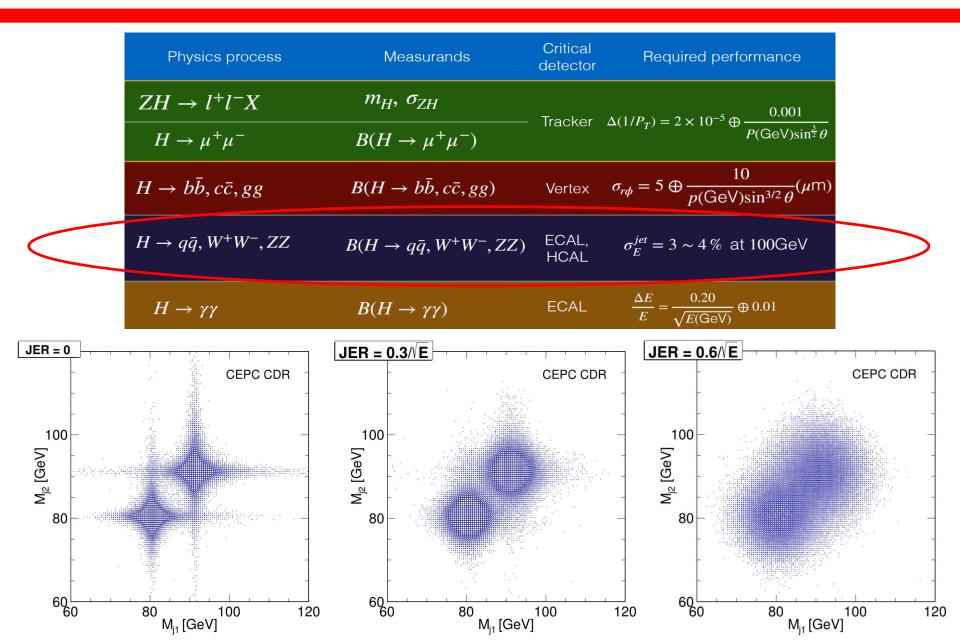
Haijun Yang (SJTU) for CEPC Calo Working Group

CEPC CDR International Review Meeting IHEP, September 13-15, 2018

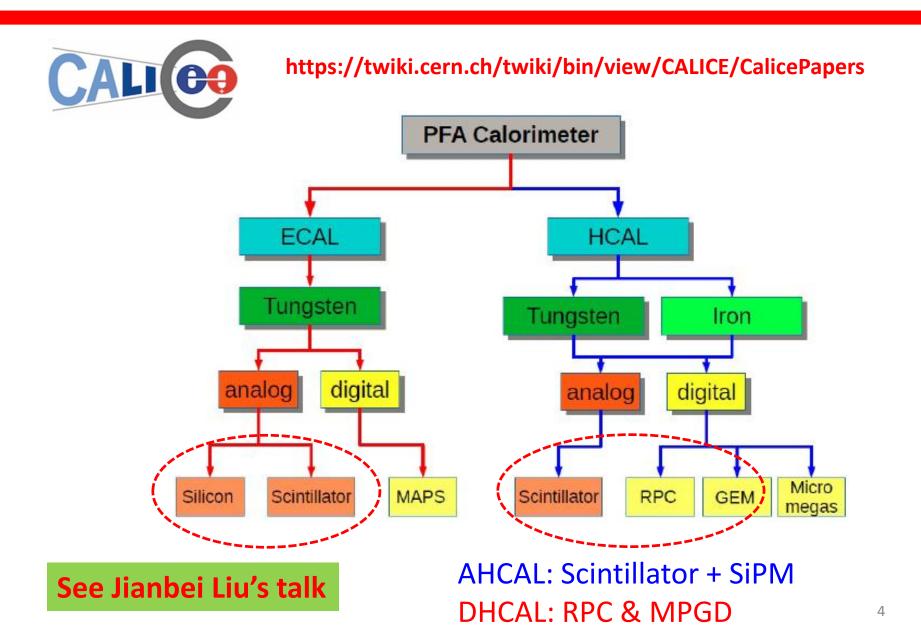
Outline

- Requirements of CEPC Calorimeters
- HCAL Geometry and Optimization
- Semi-Digital HCAL based on RPC
- Semi-Digital HCAL based on THGEM
- Analog HCAL based on Scintillator + SiPM
- Summary and Future Plans

Requirements of CEPC Calorimeters



Options of PFA-based HCAL



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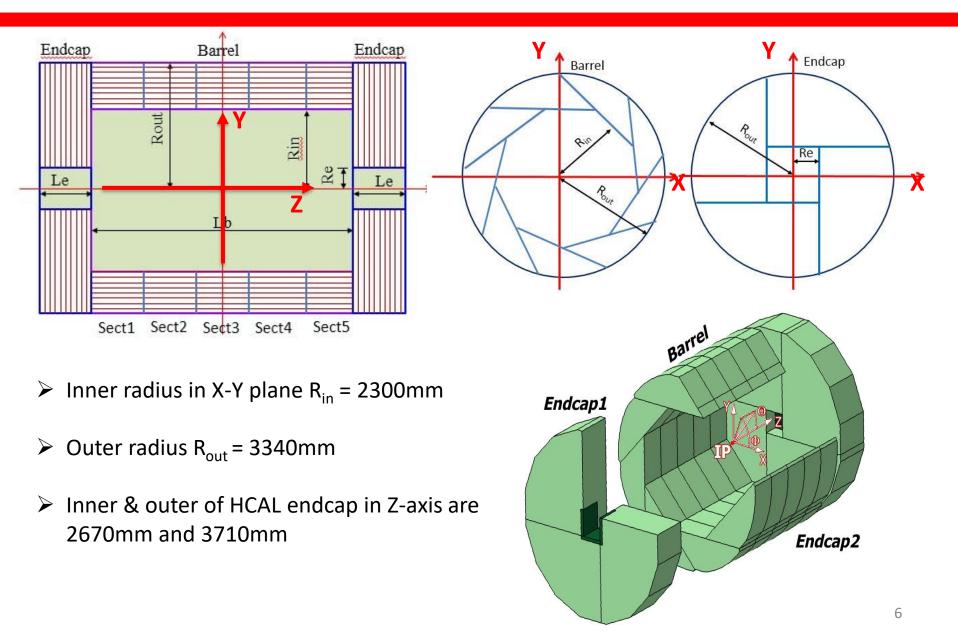
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CEPC HCAL Geometry

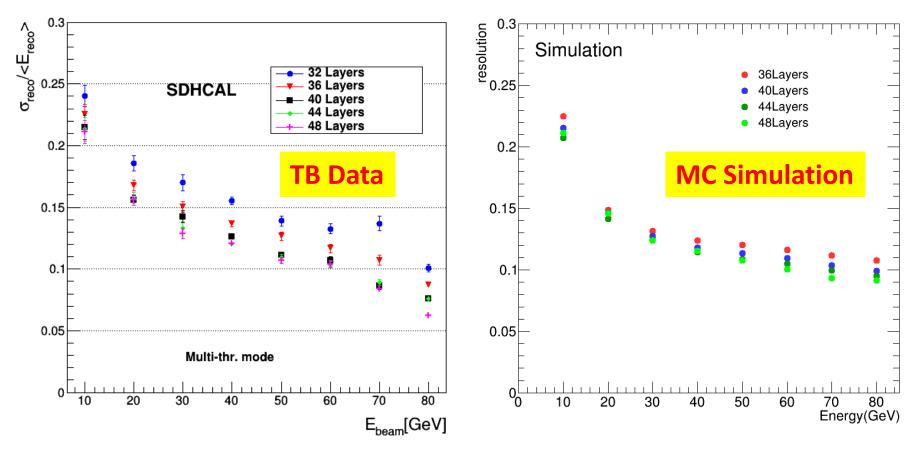


Optimization of SDHCAL Layers

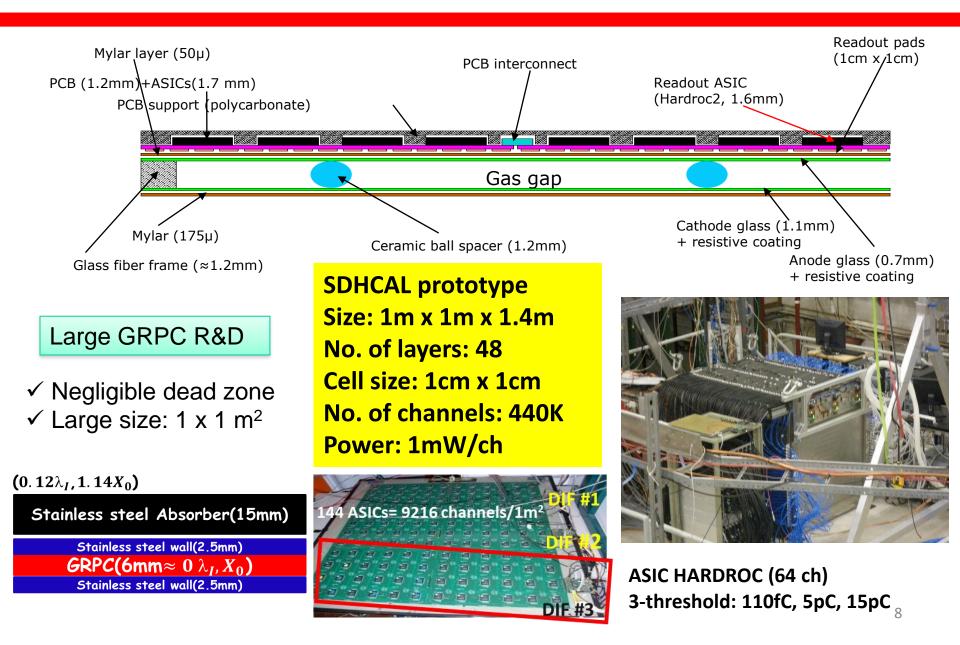
 $\begin{array}{l} \textbf{(0.12}\lambda_{I},\textbf{1.14}X_{0}\textbf{)}\\ \textbf{Stainless steel Absorber(15mm)}\\ \textbf{Stainless steel wall(2.5mm)}\\ \textbf{GRPC(6mm} \approx 0 \ \lambda_{I}, X_{0}\textbf{)}\\ \textbf{Stainless steel wall(2.5mm)}\\ \textbf{Stainless steel wall(2.5mm)}\end{array}$

→ SDHCAL has 48 layers:

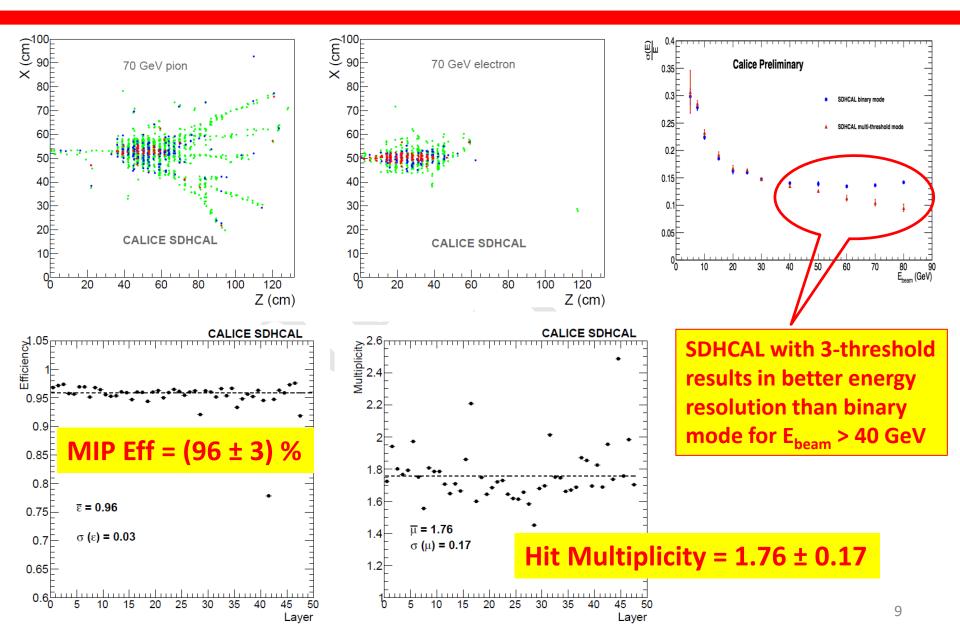
- 6mm RPC+20mm absorber (steel)
- **→**40-layer yields decent energy resolution



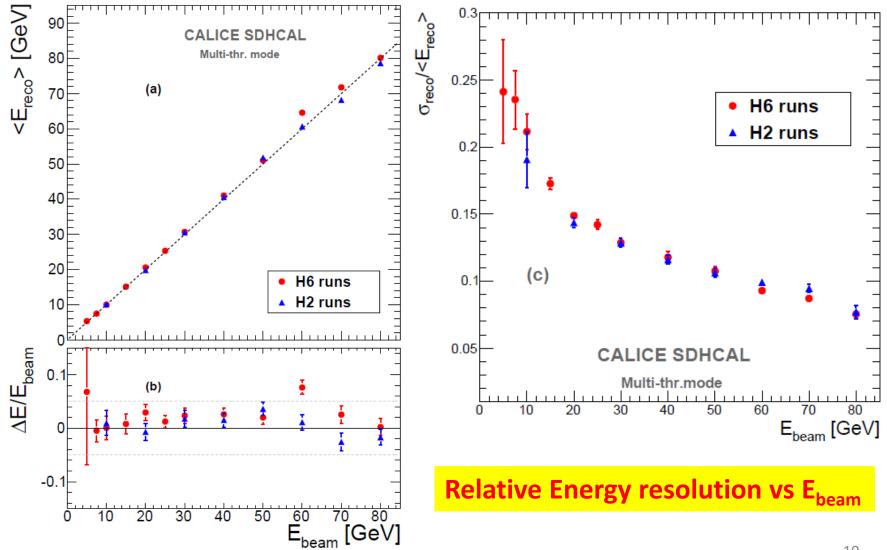
SDHCAL based on RPC



Performance of SDHCAL

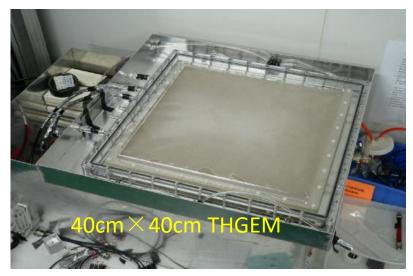


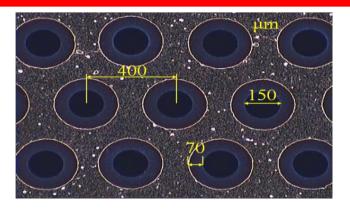
Performance of SDHCAL

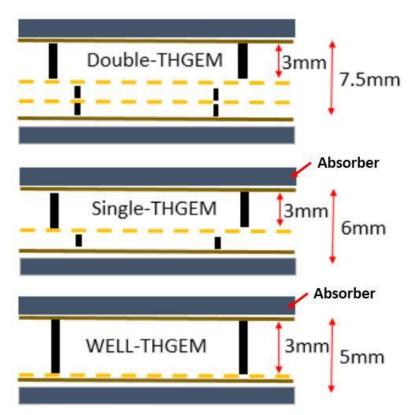


DHCAL based on THGEM

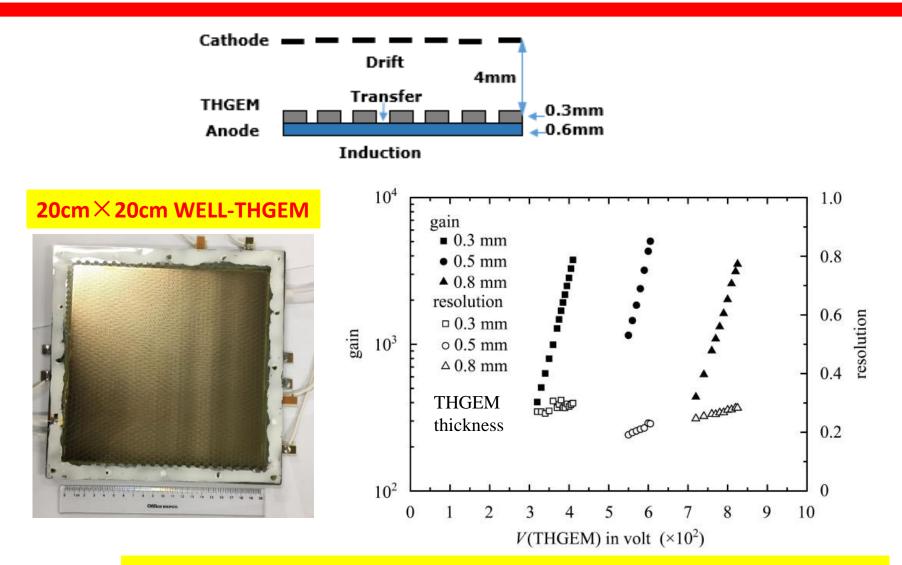
- Three THGEM options are explored:
 - Double THGEM
 - Single THGEM
 - WELL THGEM
- WELL-THGEM is optimal choice Thinner, lower discharge
- 40 × 40 cm² of THGEM (below) was produced in China







DHCAL based on THGEM



WELL-THGEM: ⁵⁵Fe (Xray ~ KeV), gain ~ 5000, energy resolution is 20%-25% high rate ~ 1 MHz/cm², MIP eff > 95%

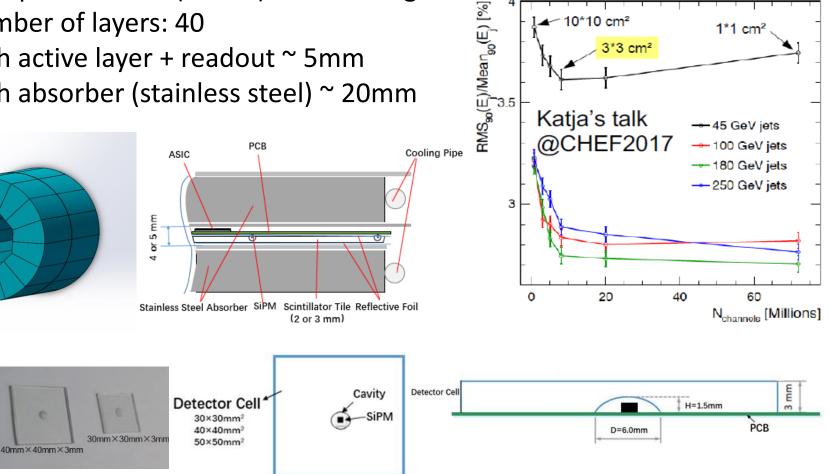
AHCAL based on Scintillator + SiPM

AHCAL (Scintillator + SiPM) for CEPC

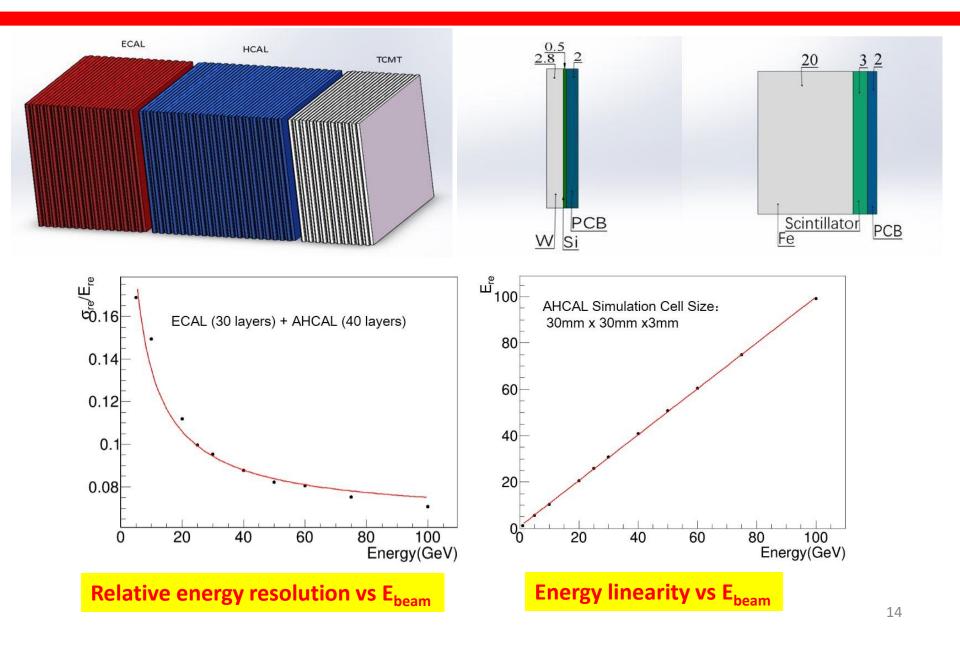
- Scintillator cell size: 3x3cm², 4x4cm², 5x5cm²
- 32 super modules (16+16) in barrel region
- Number of layers: 40

50mm×50mm×3mn

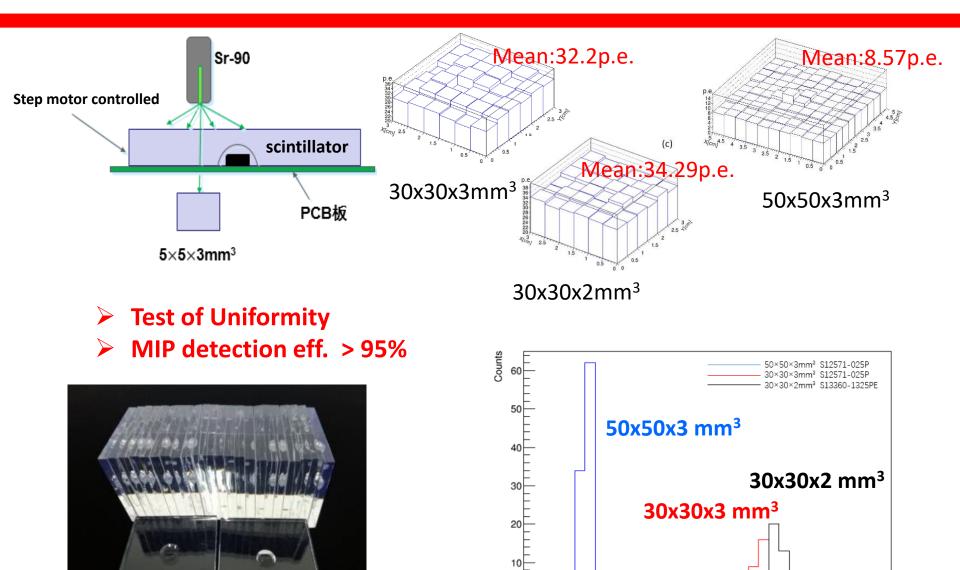
- Each active layer + readout ~ 5mm
- Each absorber (stainless steel) ~ 20mm



AHCAL based on Scintillator + SiPM



Test: Scintillator + SiPM



0^L

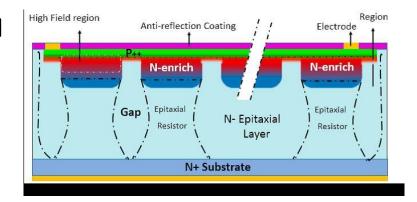
p.e. number

Development of SiPM

Hamamatsu MPPC vs NDL EQR SiPM (epitaxial quenching resistors)

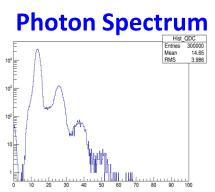
- Short recovery time
- High counting rate capability





Hamamatsu MPPC





	NDL SIPIVI		Hamamatsu WIPPC		
Effective Active	11-3030 B-S	22-1414 B-S	S13360-3025PE	S13360-1325PE	
Area	3.0×3.0 mm ²	1.4×1.4 mm ² (2×2 Array)	3.0×3.0 mm ²	1.3×1.3 mm ²	
Effective Pitch	1 0 μm	10 µm	25 µm	25µm	
Micro-cell Number	90000	19600	14400	2668	
Fill Factor	40%	40%	47%	47%	
Breakdown Voltage (V _b)	23.7±0.1V	23.7±0.1V	53±5V	53±5V	
Measurement Overvoltage (V)	3.3	3.3	5	5	
Peak PDE	27%@420nm	35%@420nm	25%@450nm	25%@450nm	
Max. Dark Count (kcps)	< 7000	<1500	1200	210	
Gain	2×105	2×10 ⁵	7.0×10 ⁵	7.0×10 ⁵	
Temp. Coef. For V _b	17mV/°C	17mV/°C	54mV/°C	54mV/°C	

NDL EQR-SiPM VS Hamamatsu MPPC

NDI SIPM

Estimated HCAL Channels

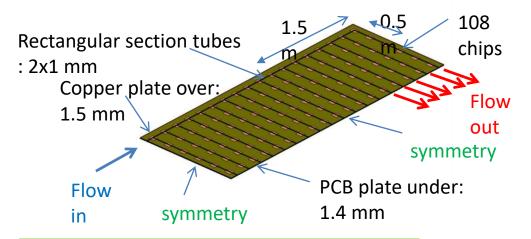
 - HCAL Barrel, R_{in} = 2.3m, R_{out} = 3.34m, length = 2.67*2=5.34m, N_{layer}=40 Area of HCAL barrel = 2*PI*[(R_{in}+R_{out})/2]*L*N_{layer} = 3782 m²
- HCAL Endcap (2), R_{in} = 0.35m, R_{out} = 3.34m, N_{layer}=40 Area of HCAL endcap = 2*PI*(R_{out}*R_{out} - R_{in}*R_{in})*N_{layer} = 2772 m²

Cell Size \ channels	HCAL Barrel	HCAL Endcap	Channels (N _{ch})	Power AHCAL	Power SDHCAL
1cm x 1cm	37.82M	27.72M	65.5M		110 kW
2cm x 2cm	9.455M	6.93M	16.4M		52 kW
3cm x 3cm	4.2M	3.08M	7.3M	110 kW	43 kW
4cm x 4cm	2.36M	1.73M	4.1M	88 kW	
5cm x 5cm	1.51M	1.11M	2.6M	77 kW	

Power Consumption (rough estimation): AHCAL: 7mW/ch * N_{ch3} + 9W/DIF/m² * 6554 (59kW) SDHCAL: 1mW/ch * N_{ch1} + 5.4W/DIF/m² * 6554 (35.4kW)

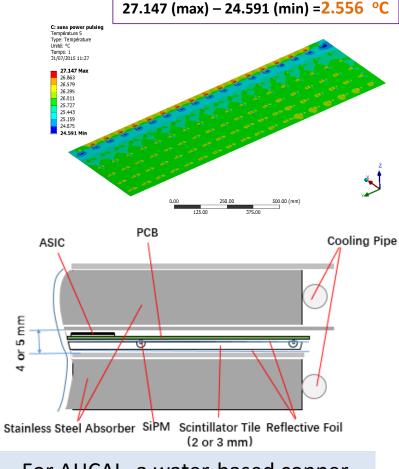
Active Cooling

Cooling may become necessary if it is operating at continuous mode (CEPC)



- A water-based cooling system inside copper tubes in contact with the ASICs to absorb excess heat.
- Temperature distribution in an active layer of the SDHCAL.

Water cooling : h = 10000 W/m²/k Thermal load : 80 mW/chip



 For AHCAL, a water-based copper cooling system embedded in the stainless steel absorber.

Summary and Future Plans

- Semi-Digital HCAL (RPC, THGEM) and Analog HCAL (Scintillator+SiPM) are considered as options of CEPC hadron calorimeter, both conceptual designs with 40 layers can reach required energy resolution.
- Baseline cell size for SDHCAL and AHCAL are 1cm ×1cm and 3cm×3cm, respectively.

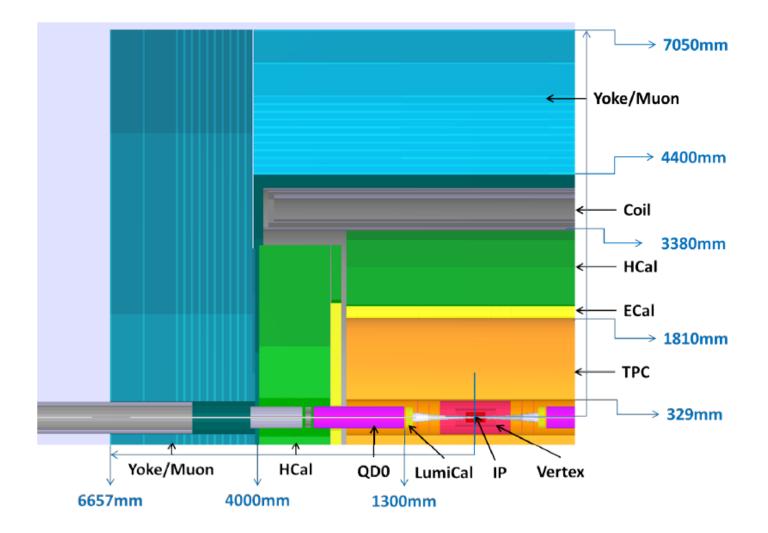
Future plans:

- Optimization of cell size and number of channels
- Design of low power ASIC chip
- Design of active cooling system

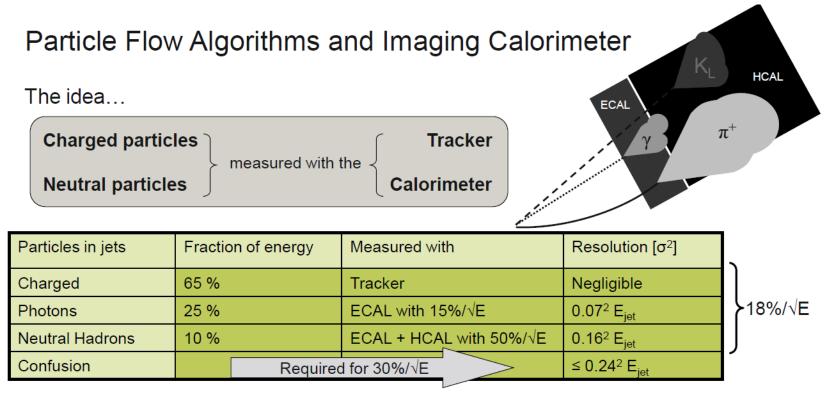
Thanks for your attention !

Backup!

Schematic of CEPC Detector



Particle Flow Algorithm

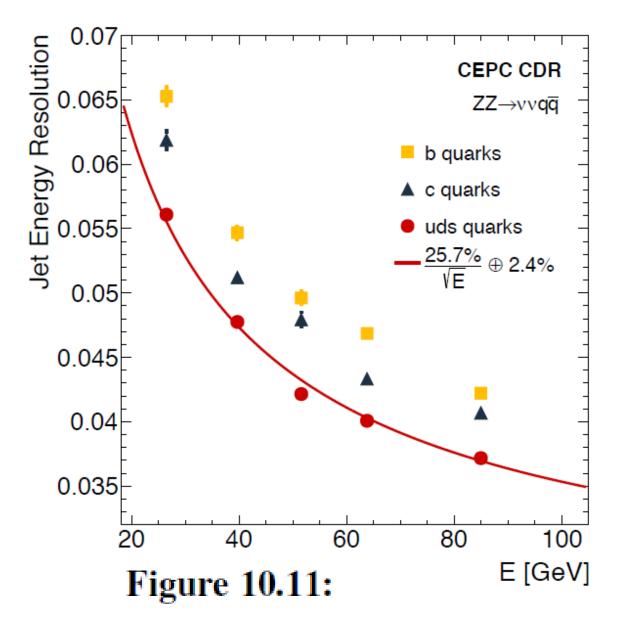


Requirements for detector system

- \rightarrow Need excellent tracker and high B field
- \rightarrow Large R_I of calorimeter
- \rightarrow Calorimeter inside coil
- \rightarrow Calorimeter as dense as possible (short X₀, λ_1).
- → Calorimeter with **extremely fine segmentation**

thin active medium

Particle Flow Algorithm (Arbor)



Particle Flow Algorithm (Arbor)

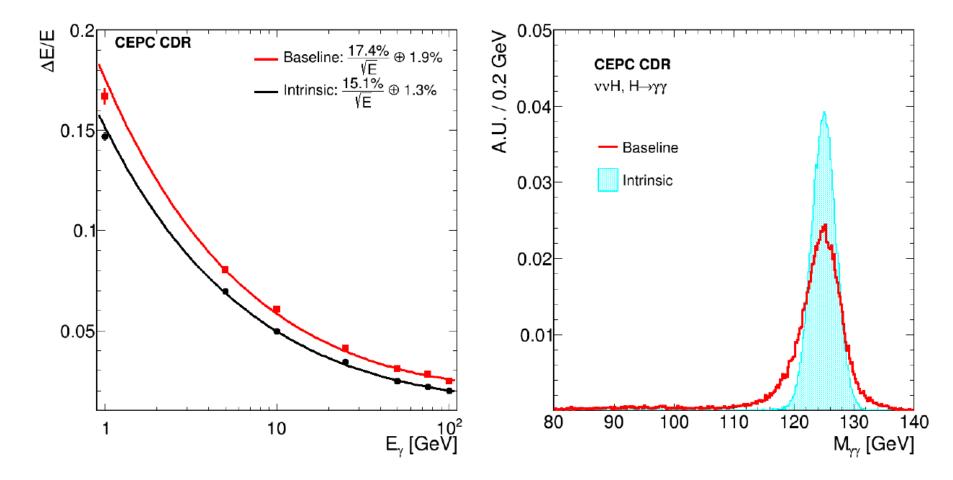


Figure 10.9: (a) The energy resolution of unconverted photons

Data Rate Estimation

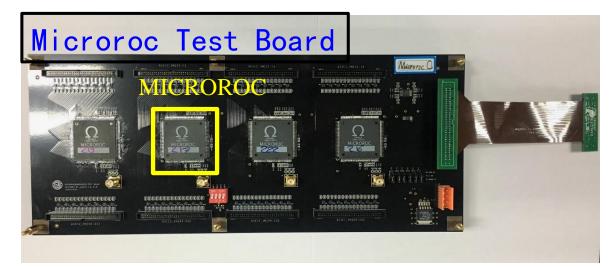
	Total #	Occupancy	Nbit	# Channels	Volume	Data rate
	channels		/channel	readout/evt	/evt	@100 kHz
	$M(10^{6})$	%		$k(10^3)$	MBytes	GBytes/s
Vertex	690	0.3	32	2070	8.3	830
Silicon						
Tracker						
Barrel	3238	$0.01 \sim 1.6$	32	1508	3.15	315
Endcap	1238	$0.01\sim 0.8$	32	232	0.4	40
TPC	2	0.1-8	30	1375	5	500
Drift						
Chamber	0.056	5-10	480	?	3	300
ECAL						
Barrel	17/7.7	0.17	32	28.8/13.1	0.117/0.053	11.7/5.3
Endcap	7.3/3.3	0.31	32	22.4/10.2	0.090/0.041	9.0/4.1
AHCAL						
Barrel	3.6	0.02	32	0.72	0.0029	0.3
Endcap	3.1	0.12	32	3.72	0.015	1.5
DHCAL						
Barrel	32	0.004	2	1.28	0.00032	0.03
Endcap	32	0.01	2	3.2	0.0008	0.08
Dual						
Readout						
Calorimeter	22	0.4-1.6	64	88-352	0.704-2.8	70-280
Muon						
Barrel	4.9	0.0002	24	0.01	< 0.0001	< 0.01
Endcap	4.6	0.0002	24	0.01	< 0.0001	< 0.01

Table 8.1: CEPC DAQ Data Rate Estimation. TPC and drift chamber are options of outer side tracker. With the level-1 trigger operating at 100 kHz, the total raw data rate is 2 TBytes/s.

Readout ASIC

Readout ASIC	Channels	Dynamic Range	Threshold	Consumption
GASTONE	64	200fC	Single	2.4mW/ch
VFAT2	128	18.5fC	Single	1.5mW/ch
DIRAC	64	200fC for MPGD	Multiple	1mW/ch, 10µW/ch
DCAL	64	20fC~200fC	Single	
HARDROC2	64	10fC~10pC	Multiple	$1.42 \text{mW/ch}, 10 \mu \text{W/ch}$
MICROROC	64	1fC~500fC	Multiple	335µW/ch, 10µW/ch

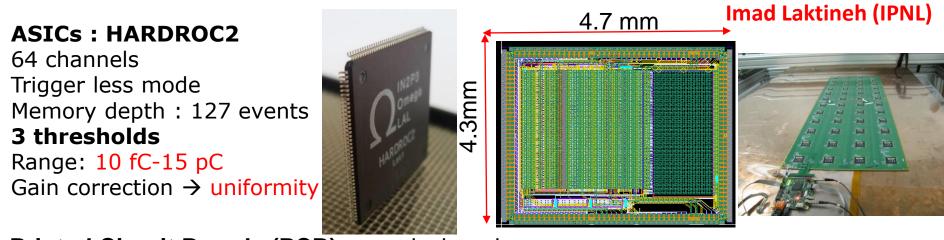
Considered the multi-thresholds readout, dynamic range and power consumption, MICROROC is an appropriate readout ASIC



MICROROC Parameters

- □ Thickness: 1.4mm
- □ 64 Channels
- □ 3 threshold per channel
- □ 128 hit storage depth
- Minimum distinguishable charge:2fC

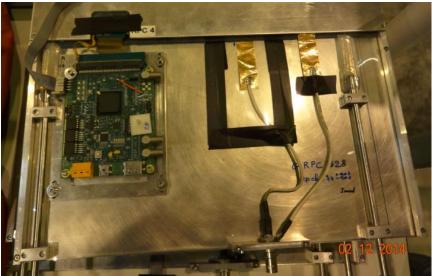
Electronics Readout



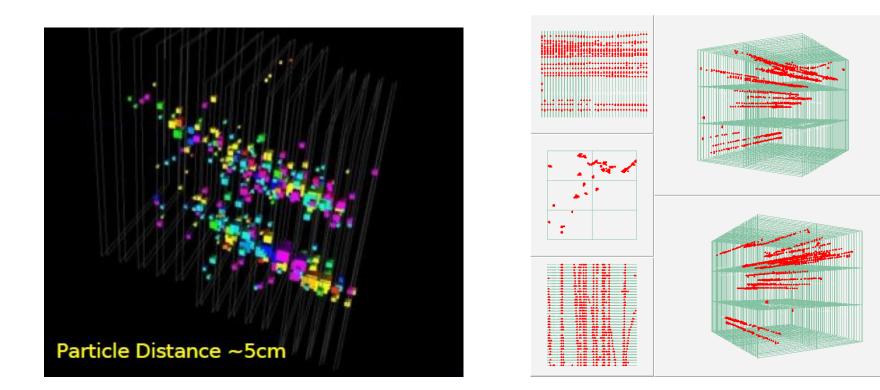
Printed Circuit Boards (PCB) were designed to reduce the cross-talk with 8-layer structure and buried vias.

Tiny connectors were used to connect the PCB two by two so the 24X2 ASICs are daisy-chained. $1 \times 1m^2$ has 6 PCBs and 9216 pads.

DAQ board (DIF) was developed to transmit fast commands and data to/from ASICs.



Imaging Calorimeters



Two electrons ~ 5cm apart CALICE SiW ECAL ~20 muons in 1m² area CALICE RPC DHCAL

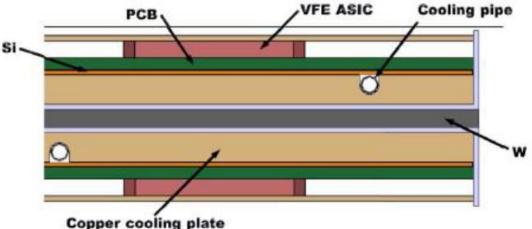
This is exactly what PFA needs: distinguishing individual showers within jet environment, in order to get excellent jet energy/mass resolution

Active Cooling

- CEPC is designed to operate at continuous mode with beam crossing rate: 2.8×10⁵ Hz. Power pulsing will not work at CEPC.
- Compare to ILD, the power consumption of VFE readout electronics at CEPC is about two orders of magnitude higher, hence it requires an active cooling
 - Evaporative CO₂ cooling in thin pipes embedded in Copper exchange plate.
 - For CMS-HGCAL design: heat extraction of 33 mW/cm², allows operation with $6 \times 6 \text{ mm}^2$ pixels with a safety margin of 2
- > To be modelled for Mokka simulation

Transverse view of the slab with one absorber and two active layers.

➔ The silicon sensors are glued to PCB with VFE chips, cooled by the copper plates with CO₂ cooling pipes.



Extra Info

N	0 .¢	Detector Cell.	MPPC Type	Reflective Foil Type.	Mean Np.e.*	Polishing Methods.
1	l.o	$30 \times 30 \times 3 \mathrm{mm}^{3_{\varphi}}$	S12571-025P.	ESR	31.39±0.65¢	Ultra Precise Polishing.
2	2.0	$30 \times 30 \times 3 \mathrm{mm}^{3}$	S12571-025P.	ESR.	22.55±0.7.	Precise Polishing.
3	3₽	$30 \times 30 \times 3 \mathrm{mm}^{3_{\varphi}}$	S12571-025P _e	ESR.	18.92±0.39¢	Rough Polishing.
4	1 .0	$30 \times 30 \times 3 \mathrm{mm}^{3}$	S12571-025P.	TYVEK	13.63±0.33¢	Precise Polishing.
5	5₽	$40 \times 40 \times 3 \mathrm{mm}^{3_{\varphi}}$	S12571-025P _e	ESR.	14.89±0.73.	Precise Polishing.
6	5.	$50 \times 50 \times 3 \mathrm{mm}^{3}$	S12571-025P _e	ESR₀	9.87±0.43.	Precise Polishing.
7	7>	$30 \times 30 \times 2 \text{mm}^{3_{\varphi}}$	S13360-1325PE _e	ESR.	33.89±0.49¢	Precise Polishing.

Material	$\lambda_I(\text{cm})$	$X_0(cm)$	λ_I/X_0
Fe	16.77	1.76	9.5
Pb	17.09	0.56	30.52
W	9.95	0.35	28.4

